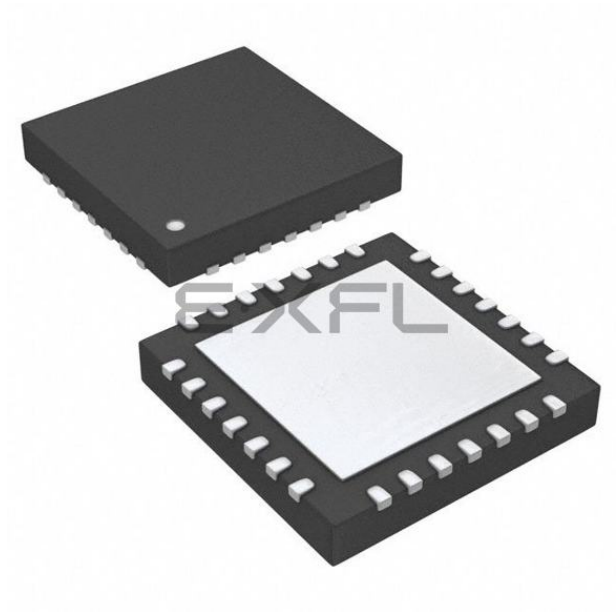
Microchip Technology - PIC24FJ256GA702T-I/MV Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

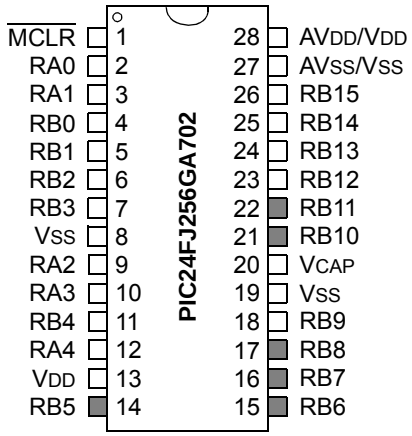
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	22
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj256ga702t-i-mv

Pin Diagrams (PIC24FJ256GA702 Devices)

28-Pin SOIC, SSOP, SPDIP



Legend: See Table 2 for a complete description of pin functions. Pinouts are subject to change.

Note: Gray shading indicates 5.5V tolerant input pins.

TABLE 2: COMPLETE PIN FUNCTION DESCRIPTIONS (PIC24FJ256GA702 SOIC, SSOP, SPDIP)

Pin	Function	Pin	Function
1	MCLR	15	PGC3/**RP6**/ASCL1/OCM1F/RB6
2	VREF+/CVREF+/AN0/C3INC/**RP26**/CTED1/RA0	16	**RP7**/OCM1A/CTED3/INT0/RB7
3	VREF-/CVREF-/AN1/C3IND/**RP27**/CTED2/RA1	17	TCK/**RP8**/SCL1/OCM1B/CTED10/RB8
4	PGD1/AN2/CTCMP/C2INB/**RP0**/RB0	18	TDO/C1INC/C2INC/C3INC/TMPRN/**RP9**/SDA1/T1CK/CTED4/RB9
5	PGC1/AN1-/AN3/C2INA/**RP1**/CTED12/RB1	19	VSS
6	AN4/C1INB/**RP2**/SDA2/CTED13/RB2	20	VCAP
7	AN5/C1INA/**RP3**/SCL2/CTED8/RB3	21	PGD2/TDI/**RP10**/OCM1C/CTED11/RB10
8	VSS	22	PGC2/TMS/REFI1/**RP11**/CTED9/RB11
9	OSCI/CLKI/C1IND/RA2	23	AN8/LVDIN/**RP12**/RB12
10	OSCO/CLKO/C2IND/RA3	24	AN7/C1INC/**RP13**/OCM1D/CTPLS/RB13
11	SOSCI/**RP4**/RB4	25	CVREF/AN6/C3INB/**RP14**/CTED5/RB14
12	SOSCO/PWRLCLK/RA4	26	AN9/C3INA/**RP15**/CTED6/RB15
13	VDD	27	AVSS/VSS
14	PGD3/**RP5**/ASDA1/OCM1E/RB5	28	AVDD/VDD

Legend: **RPn** represents remappable pins for Peripheral Pin Select (PPS) functions.

Note: Pinouts are subject to change.

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 25V-50V capacitor is recommended. The capacitor should be a low-ESR device with a self-resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 BULK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a bulk capacitance of 10 μF or greater located near the MCU. The value of the capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. Typical values range from 10 μF to 47 μF. The capacitor should be ceramic and have a voltage rating of 25V or more to reduce DC bias effects (see **Section 2.4.1 "Considerations for Ceramic Capacitors"**).

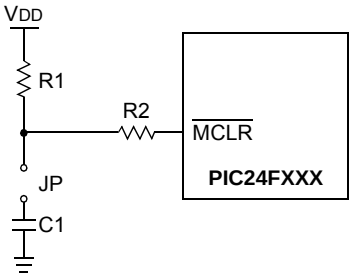
2.3 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions: device Reset, and device programming and debugging. If programming and debugging are not required in the end application, a direct connection to VDD may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{\text{MCLR}}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of a $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

REGISTER 7-1: RCON: RESET CONTROL REGISTER

R/W-0	R/W-0	R/W-1	R/W-0	U-0	U-0	R/W-0	R/W-0
TRAPR(1)	IOPUWR(1)	SBOREN(5)	RETEN(2)	—	—	CM(1)	VREGS(3)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR(1)	SWR(1)	SWDTEN(4)	WDTO(1)	SLEEP(1)	IDLE(1)	BOR(1)	POR(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit(1)
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Register Access Reset Flag bit(1)
1 = An illegal opcode detection, an illegal address mode or Uninitialized W register is used as an Address Pointer and caused a Reset
0 = An illegal opcode or Uninitialized W register Reset has not occurred

bit 13 **SBOREN:** Software Control Over the BOR Function bit(5)
1 = BOR is enabled
0 = BOR is disabled

bit 12 **RETEN:** Retention Mode Enable bit(2)
1 = Retention mode is enabled while device is in Sleep mode (1.2V regulator supplies to the core)
0 = Retention mode is disabled; normal voltage levels are present

bit 11-10 **Unimplemented:** Read as '0'

bit 9 **CM:** Configuration Word Mismatch Reset Flag bit(1)
1 = A Configuration Word Mismatch Reset has occurred
0 = A Configuration Word Mismatch Reset has not occurred

bit 8 **VREGS:** Fast Wake-up from Sleep bit(3)
1 = Fast wake-up is disabled (lower power)
0 = Fast wake-up is enabled (higher power)

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit(1)
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software RESET (Instruction) Flag bit(1)
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the $\overline{\text{LPCFG}}$ Configuration bit is '1' (unprogrammed), the retention regulator is disabled and the RETEN bit has no effect. Retention mode preserves the SRAM contents during Sleep.

3: Re-enabling the regulator after it enters Standby mode will add a delay, TVREG, when waking up from Sleep. Applications that do not use the voltage regulator should set this bit to prevent this delay from occurring.

4: If the FWDTEN<1:0> Configuration bits are '11' (unprogrammed), the WDT is always enabled**,** regardless of the SWDTEN bit setting.

5: The BOREN<1:0> (FPOR<1:0>) Configuration bits must be set to '01' in order for SBOREN to have an effect.

9.0 OSCILLATOR CONFIGURATION

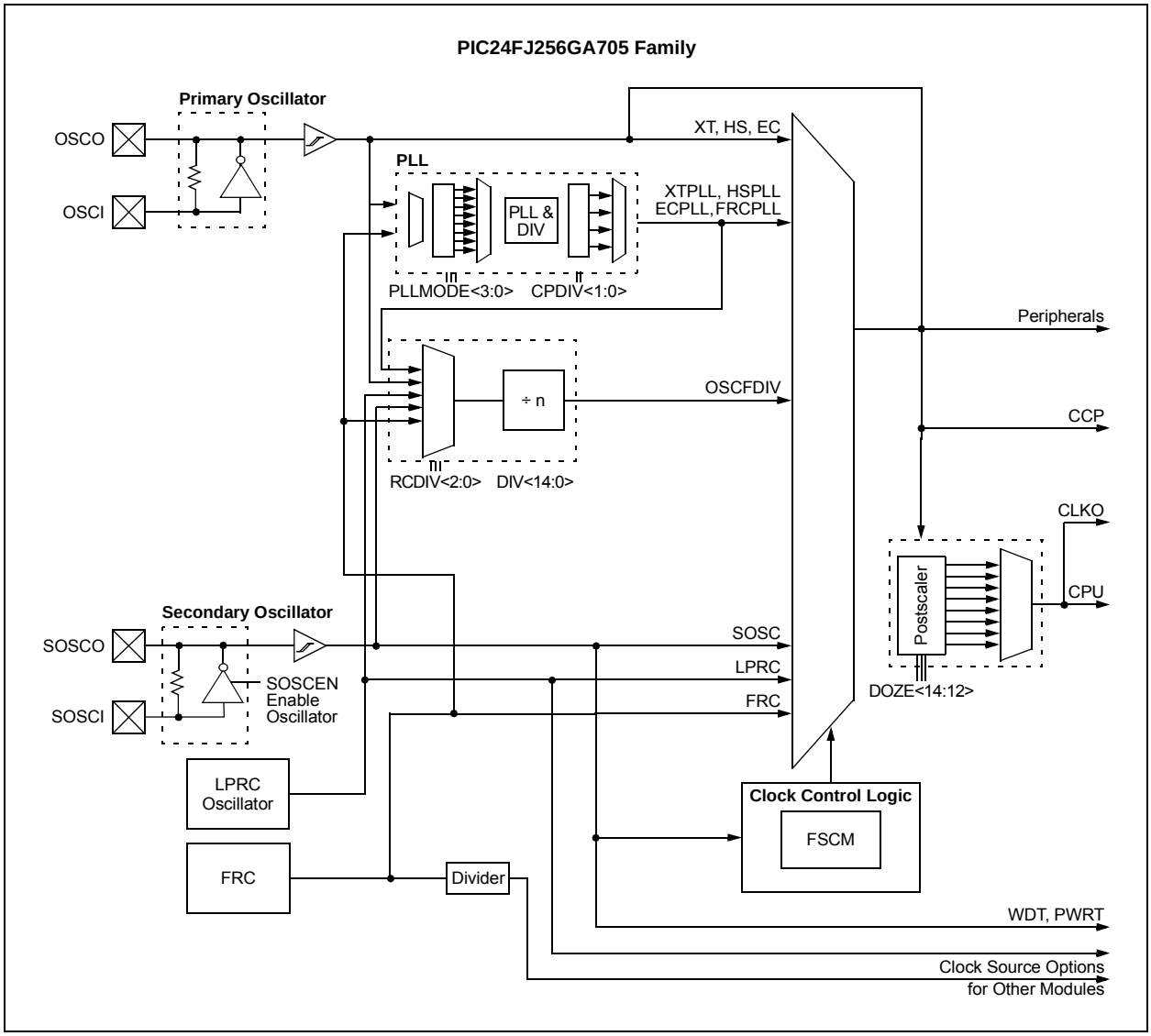
Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Oscillator"** (DS39700), which is available from the Microchip web site (www.microchip.com). The information in this data sheet supersedes the information in the FRM.

The oscillator system for the PIC24FJ256GA705 family devices has the following features:

- An On-Chip PLL Block to provide a Range of Frequency Options for the System Clock
- Software-Controllable Switching between Various Clock Sources
- Software-Controllable Postscaler for Selective Clocking of CPU for System Power Savings
- A Fail-Safe Clock Monitor (FSCM) that Detects Clock Failure and Permits Safe Application Recovery or Shutdown
- A Separate and Independently Configurable System Clock Output for Synchronizing External Hardware

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: PIC24FJ256GA705 FAMILY CLOCK DIAGRAM



A recommended code sequence for a clock switch includes the following:

1. Disable interrupts during the OSCCON register unlock and write sequence.
2. Execute the unlock sequence for the OSCCON high byte by writing 78h and 9Ah to OSCCON<15:8> in two back-to-back instructions.
3. Write the new oscillator source to the NOSCx bits in the instruction immediately following the unlock sequence.
4. Execute the unlock sequence for the OSCCON low byte by writing 46h and 57h to OSCCON<7:0> in two back-to-back instructions.
5. Set the OSWEN bit in the instruction immediately following the unlock sequence.
6. Continue to execute code that is not clock-sensitive (optional).
7. Invoke an appropriate amount of software delay (cycle counting) to allow the selected oscillator and/or PLL to start and stabilize.
8. Check to see if OSWEN is '0'. If it is, the switch was successful. If OSWEN is still set, then check the LOCK bit to determine the cause of the failure.

The core sequence for unlocking the OSCCON register and initiating a clock switch is shown in Example 9-1.

EXAMPLE 9-1: BASIC CODE SEQUENCE FOR CLOCK SWITCHING

```
;Place the new oscillator selection in W0
;OSCCONH (high byte) Unlock Sequence
MOV         #OSCCONH, w1
MOV         #0x78, w2
MOV         #0x9A, w3
MOV.b       w2, [w1]
MOV.b       w3, [w1]
;Set new oscillator selection
MOV.b       WREG, OSCCONH
;OSCCONL (low byte) unlock sequence
MOV         #OSCCONL, w1
MOV         #0x46, w2
MOV         #0x57, w3
MOV.b       w2, [w1]
MOV.b       w3, [w1]
;Start oscillator switch operation
BSET        OSCCON, #0
```

REGISTER 10-6: PMD6: PERIPHERAL MODULE DISABLE REGISTER 6

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	SPI3MD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as '0'

bit 0 **SPI3MD:** SPI3 Module Disable bit
1 = Module is disabled
0 = Module power and clock sources are enabled

REGISTER 10-7: PMD7: PERIPHERAL MODULE DISABLE REGISTER 7

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	—	DMA1MD	DMA0MD	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5 **DMA1MD:** DMA1 Controller (Channels 4 through 7) Disable bit
1 = Controller is disabled
0 = Controller power and clock sources are enabled

bit 4 **DMA0MD:** DMA0 Controller (Channels 0 through 3) Disable bit
1 = Controller is disabled
0 = Controller power and clock sources are enabled

bit 3-0 **Unimplemented:** Read as '0'

11.1.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically, this instruction would be a NOP.

11.1.2 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, each port pin can also be individually configured for either a digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired digital only pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

11.2 Configuring Analog Port Pins (ANSx)

The ANSx and TRISx registers control the operation of the pins with analog function. Each port pin with analog function is associated with one of the ANSx bits, which decide if the pin function should be analog or digital. Refer to Table 11-1 for detailed behavior of the pin for different ANSx and TRISx bit settings.

When reading the PORTx register, all pins configured as analog input channels will read as cleared (a low level).

11.2.1 ANALOG INPUT PINS AND VOLTAGE CONSIDERATIONS

The voltage tolerance of pins used as device inputs is dependent on the pin's input function. Most input pins are able to handle DC voltages of up to 5.5V, a level typical for digital logic circuits. However, several pins can only tolerate voltages up to VDD. Voltage excursions beyond VDD on these pins should always be avoided.

Table 11-2 summarizes the different voltage tolerances. For more information, refer to **Section 32.0 "Electrical Characteristics"** for more details.

TABLE 11-1: CONFIGURING ANALOG/DIGITAL FUNCTION OF AN I/O PIN

Pin Function	ANSx Setting	TRISx Setting	Comments
Analog Input	1	1	It is recommended to keep ANSx = 1.
Analog Output	1	1	It is recommended to keep ANSx = 1.
Digital Input	0	1	Firmware must wait at least one instruction cycle after configuring a pin as a digital input before a valid input value can be read.
Digital Output	0	0	Make sure to disable the analog output function on the pin if any is present.

TABLE 11-2: INPUT VOLTAGE LEVELS FOR PORT OR PIN TOLERATED DESCRIPTION INPUT

Port or Pin	Tolerated Input	Description
PORTB<11:10,8:5>	5.5V	Tolerates input levels above VDD; useful for most standard logic.
PORTC<9:6>		
PORTA<14:7,4:0>	VDD	Only VDD input levels are tolerated.
PORTB<15:12,9,4:0>		
PORTC<5:0>		

REGISTER 11-38: RPOR6: PERIPHERAL PIN SELECT OUTPUT REGISTER 6

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP13R5	RP13R4	RP13R3	RP13R2	RP13R1	RP13R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP12R5	RP12R4	RP12R3	RP12R2	RP12R1	RP12R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP13R<5:0>:** RP13 Output Pin Mapping bits
Peripheral Output Number n is assigned to pin, RP13 (see Table 11-7 for peripheral function numbers).

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP12R<5:0>:** RP12 Output Pin Mapping bits
Peripheral Output Number n is assigned to pin, RP12 (see Table 11-7 for peripheral function numbers).

REGISTER 11-39: RPOR7: PERIPHERAL PIN SELECT OUTPUT REGISTER 7

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP15R5	RP15R4	RP15R3	RP15R2	RP15R1	RP15R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP14R5	RP14R4	RP14R3	RP14R2	RP14R1	RP14R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

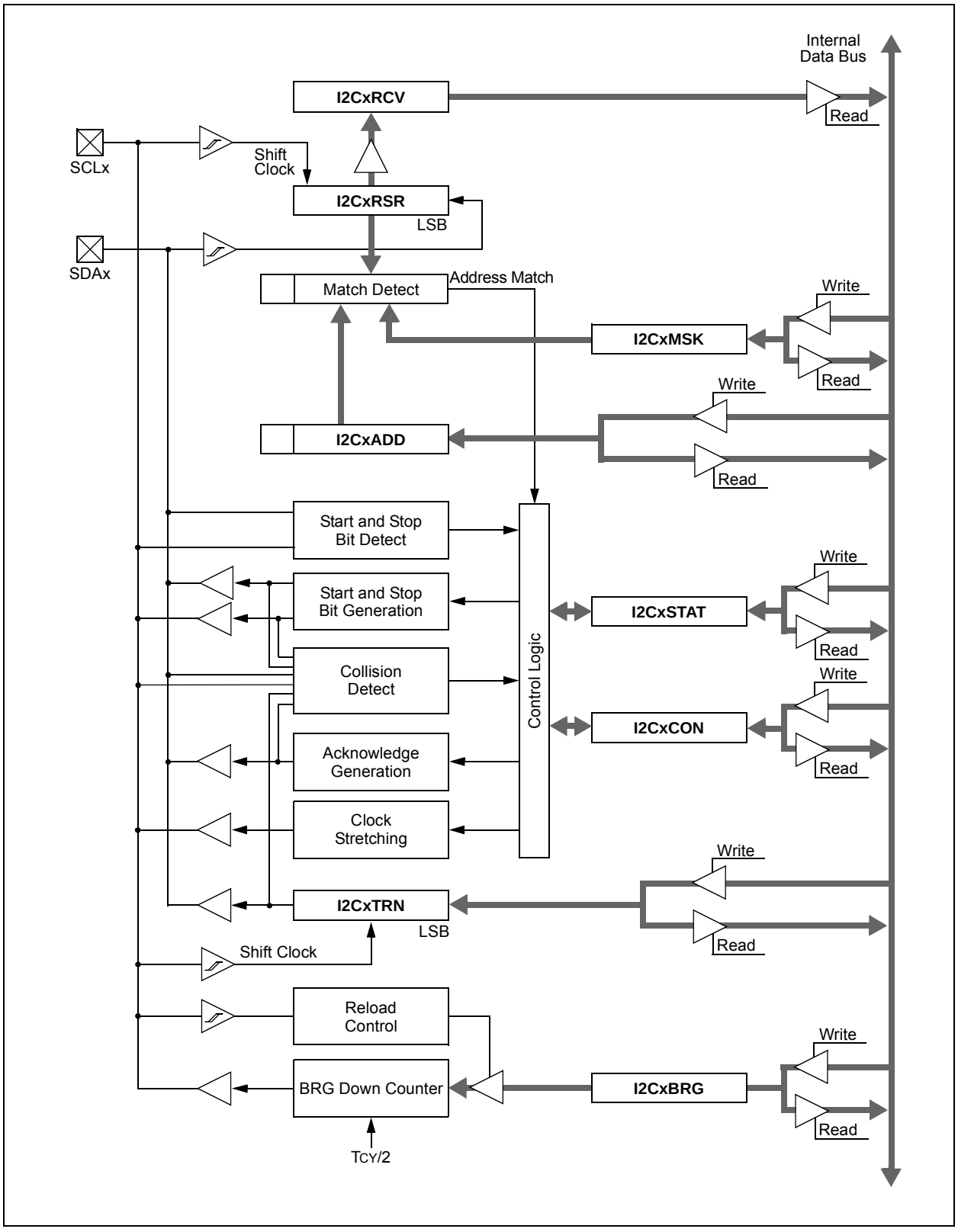
bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP15R<5:0>:** RP15 Output Pin Mapping bits
Peripheral Output Number n is assigned to pin, RP15 (see Table 11-7 for peripheral function numbers).

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP14R<5:0>:** RP14 Output Pin Mapping bits
Peripheral Output Number n is assigned to pin, RP14 (see Table 11-7 for peripheral function numbers).

FIGURE 18-1: I2Cx BLOCK DIAGRAM



REGISTER 18-1: I2CxCONL: I2Cx CONTROL REGISTER LOW

R/W-0	U-0	HC, R/W-0	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL(1)	STRICT	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	HC, R/W-0	HC, R/W-0	HC, R/W-0	HC, R/W-0	HC, R/W-0
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit (writable from software only)
1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I^2C pins are controlled by port functions

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (I^2C Slave mode only)(1)
Module resets and (I2CEN = 0) sets SCLREL = 1.
If STREN = 0:(2)
1 = Releases clock
0 = Forces clock low (clock stretch)
If STREN = 1:
1 = Releases clock
0 = Holds clock low (clock stretch); user may program this bit to '0', clock stretch at next SCLx low

bit 11 **STRICT:** I2Cx Strict Reserved Address Rule Enable bit
1 = Strict reserved addressing is enforced (for reserved addresses, refer to Table 18-2)
In Slave Mode: The device doesn't respond to reserved address space and addresses falling in that category are NACKed.
In Master Mode: The device is allowed to generate addresses with reserved address space.
0 = Reserved addressing would be Acknowledged
In Slave Mode: The device will respond to an address falling in the reserved address space. When there is a match with any of the reserved addresses, the device will generate an ACK.
In Master Mode: Reserved.

bit 10 **A10M:** 10-Bit Slave Address Flag bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Slew Rate Control Disable bit
1 = Slew rate control is disabled for Standard Speed mode (100 kHz, also disabled for 1 MHz mode)
0 = Slew rate control is enabled for High-Speed mode (400 kHz)

Note 1: Automatically cleared to '0' at the beginning of slave transmission; automatically cleared to '0' at the end of slave reception. The user software must provide a delay between writing to the transmit buffer and setting the SCLREL bit. This delay must be greater than the minimum setup time for slave transmissions, as specified in **Section 32.0 "Electrical Characteristics"**.

2: Automatically cleared to '0' at the beginning of slave transmission.

REGISTER 19-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)
1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by UEN<1:0>
0 = UARTx is disabled; all UARTx pins are controlled by port latches, UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** UARTx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)
1 = IrDA encoder and decoder are enabled
0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Enable bits
11 = UxTX, UxRX and BCLKx pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLKx pins are controlled by port latches

bit 7 **WAKE:** Wake-up on Start Bit Detect During Sleep Mode Enable bit
1 = UARTx continues to sample the UxRX pin; interrupt is generated on the falling edge, bit is cleared in hardware on the following rising edge
0 = No wake-up is enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
1 = Enables Loopback mode
0 = Loopback mode is disabled

bit 5 **ABAUD:** Auto-Baud Enable bit
1 = Enables baud rate measurement on the next character – requires reception of a Sync field (55h); cleared in hardware upon completion
0 = Baud rate measurement is disabled or completed

bit 4 **URXINV:** UARTx Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'

Note 1: If UARTEN = 1, the peripheral inputs and outputs must be configured to an available RPn/RPIn pin. For more information, see **Section 11.5 "Peripheral Pin Select (PPS)"**.
2: This feature is only available for the 16x BRG mode (BRGH = 0).

REGISTER 23-5: CLCxGLSH: CLCx GATE LOGIC INPUT SELECT HIGH REGISTER (CONTINUED)

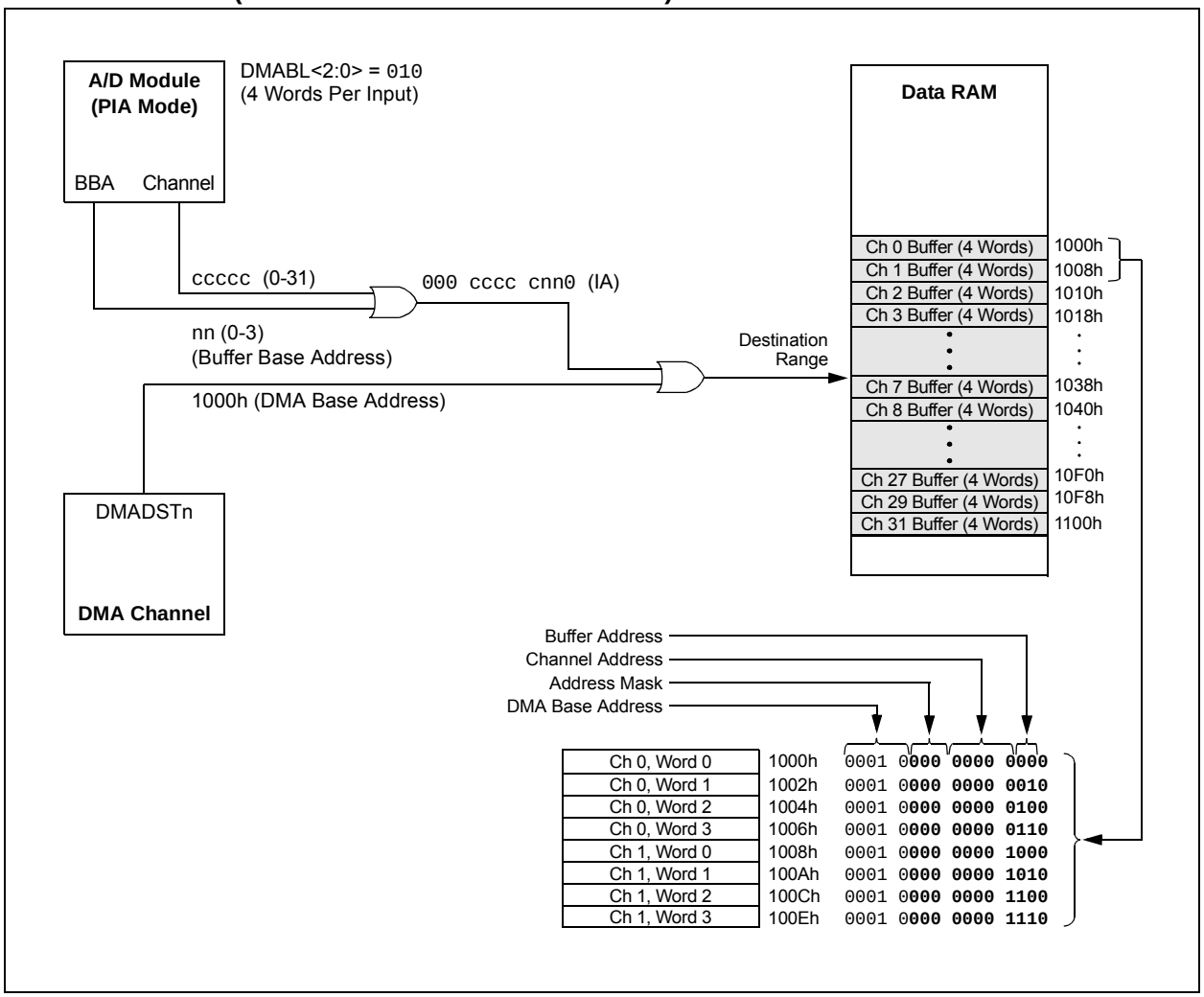
bit 3 **G3D2T:** Gate 3 Data Source 2 True Enable bit
1 = The Data Source 2 signal is enabled for Gate 3
0 = The Data Source 2 signal is disabled for Gate 3

bit 2 **G3D2N:** Gate 3 Data Source 2 Negated Enable bit
1 = The Data Source 2 inverted signal is enabled for Gate 3
0 = The Data Source 2 inverted signal is disabled for Gate 3

bit 1 **G3D1T:** Gate 3 Data Source 1 True Enable bit
1 = The Data Source 1 signal is enabled for Gate 3
0 = The Data Source 1 signal is disabled for Gate 3

bit 0 **G3D1N:** Gate 3 Data Source 1 Negated Enable bit
1 = The Data Source 1 inverted signal is enabled for Gate 3
0 = The Data Source 1 inverted signal is disabled for Gate 3

FIGURE 24-2: EXAMPLE OF BUFFER ADDRESS GENERATION IN PIA MODE (4-WORD BUFFERS PER CHANNEL)



REGISTER 24-1: AD1CON1: A/D CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	DMABM(1)	DMAEN	MODE12	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
SSRC3	SSRC2	SSRC1	SSRC0	—	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	C = Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** A/D Operating Mode bit
1 = A/D Converter is operating
0 = A/D Converter is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** A/D Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **DMABM:** Extended DMA Buffer Mode Select bit(1)
1 = Extended Buffer mode: Buffer address is defined by the DMADSTn register
0 = PIA mode: Buffer addresses are defined by the DMA Controller and AD1CON4<2:0>

bit 11 **DMAEN:** Extended DMA/Buffer Enable bit
1 = Extended DMA and buffer features are enabled
0 = Extended features are disabled

bit 10 **MODE12:** A/D 12-Bit Operation Mode bit
1 = 12-bit A/D operation
0 = 10-bit A/D operation

bit 9-8 **FORM<1:0>:** Data Output Format bits (see formats following)
11 = Fractional result, signed, left justified
10 = Absolute fractional result, unsigned, left justified
01 = Decimal result, signed, right justified
00 = Absolute decimal result, unsigned, right justified

bit 7-4 **SSRC<3:0>:** Sample Clock Source Select bits
0000 = SAMP is cleared by software
0001 = INT0
0010 = Timer3
0100 = CTMU trigger
0101 = Timer1 (will not trigger during Sleep mode)
0110 = Timer1 (may trigger during Sleep mode)
0111 = Auto-Convert mode

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** A/D Sample Auto-Start bit
1 = Sampling begins immediately after last conversion; SAMP bit is auto-set
0 = Sampling begins when SAMP bit is manually set

Note 1: This bit is only available when Extended DMA and buffer features are available (DMAEN = 1).

REGISTER 24-6: AD1CHS: A/D SAMPLE SELECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB2	CH0NB1	CH0NB0	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA2	CH0NA1	CH0NA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **CH0NB<2:0>:** Sample B Channel 0 Negative Input Select bits
1xx = Unimplemented
01x = Unimplemented
001 = Unimplemented
000 = AVSS

bit 12-8 **CH0SB<4:0>:** Sample B Channel 0 Positive Input Select bits
11110 = AVDD **(1)**
11101 = AVSS **(1)**
11100 = Band Gap Reference (VBG) **(1)**
10000-11011 = Reserved
01111 = No external channels connected (used for CTMU)
01110 = No external channels connected (used for CTMU temperature sensor)
01101 = AN13
01100 = AN12
01011 = AN11
01010 = AN10
01001 = AN9
01000 = AN8
00111 = AN7
00110 = AN6
00101 = AN5
00100 = AN4
00011 = AN3
00010 = AN2
00001 = AN1
00000 = AN0

bit 7-5 **CH0NA<2:0>:** Sample A Channel 0 Negative Input Select bits
Same definitions as for CHONB<2:0>.

bit 4-0 **CH0SA<4:0>:** Sample A Channel 0 Positive Input Select bits
Same definitions as for CHOSB<4:0>.

Note 1: These input channels do not have corresponding memory-mapped result buffers.

REGISTER 27-3: CTMUCON2L: CTMU CONTROL REGISTER 2 LOW

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	IRSTEN	—	DSCHS2	DSCHS1	DSCHS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4 **IRSTEN:** CTMU Current Source Reset Enable bit
1 = Signal selected by DSCHS<2:0> bits or IDISSEN control bit will reset CTMU edge detect logic
0 = CTMU edge detect logic will not occur

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **DSCHS<2:0>:** Discharge Source Select Bits
111 = CLC2 out
110 = CLC1 out
101 = Disabled
100 = A/D end of conversion
011 = MCCP3 auxiliary output
010 = MCCP2 auxiliary output
001 = MCCP1 auxiliary output
000 = Disabled

REGISTER 29-3: FSIGN CONFIGURATION REGISTER

U-1	U-1	U-1	U-1	U-1	U-1	U-1	U-1
—	—	—	—	—	—	—	—
bit 23							bit 16

r-0	U-1	U-1	U-1	U-1	U-1	U-1	U-1
—	—	—	—	—	—	—	—
bit 15							bit 8

U-1	U-1	U-1	U-1	U-1	U-1	U-1	U-1
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:	PO = Program Once bit	r = Reserved bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

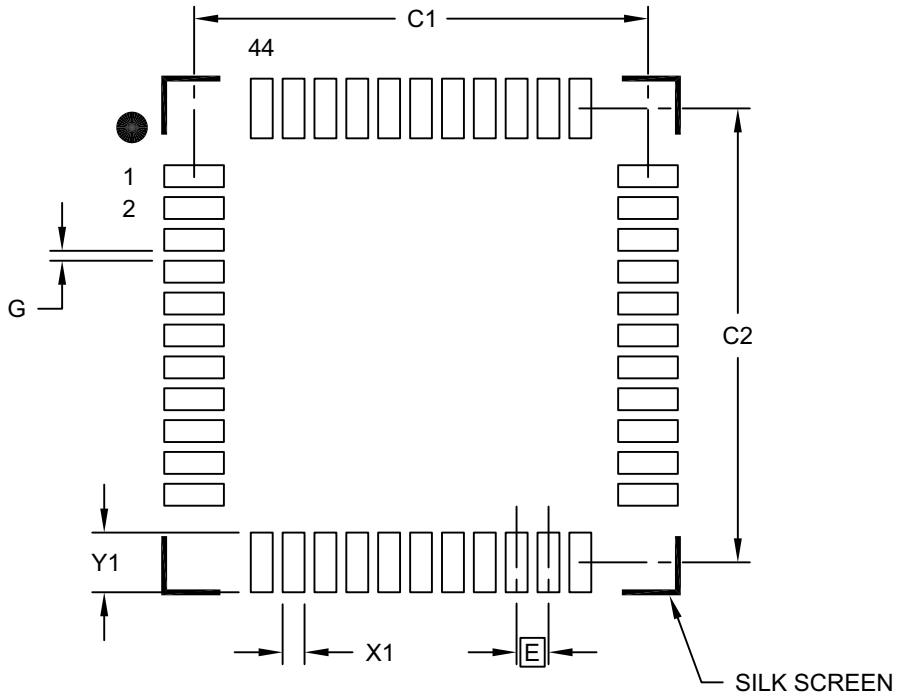
bit 23-16 **Unimplemented:** Read as ‘1’

bit 15 **Reserved:** Maintain as ‘0’

bit 14-0 **Unimplemented:** Read as ‘1’

44-Lead Plastic Thin Quad Flatpack (PT) - 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

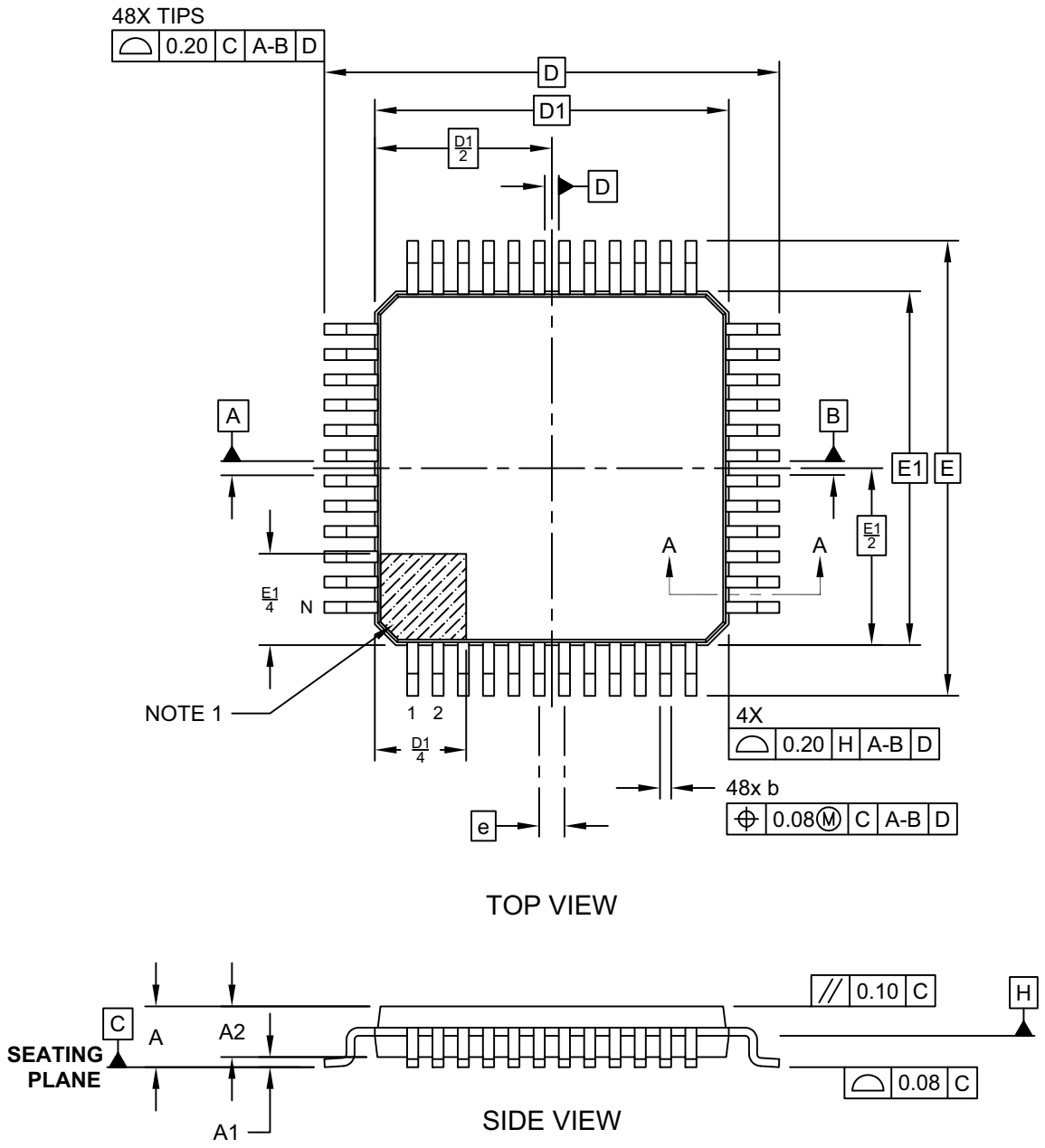
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

48-Lead Thin Quad Flatpack (PT) - 7x7x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-300-PT Rev A Sheet 1 of 2

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or Field Application Engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://microchip.com/support